



## Adherence grade

Solvent type	Product name	Polymer component (%)	Solvent	Mw	Acid Value of polymer (mgKOH/g)	T <sub>g</sub> (°C)	Doublebond equivalent (g/mol)	Feature
		OAP-5000	50	Butyl acetate	15,000	-	70	2,000
	MAP-4050	40	PGMEA /PGME	30,000	90	31	10,000	<ul style="list-style-type: none"> <li>• Good adhesion to glass, metal, inorganic film</li> <li>• Good developability and flexibility</li> <li>• Improve adhesion of pressure sensitive adhesive</li> </ul>
	MAP-7000	32	PGMEA /PGME	100,000	60	78	1,000	<ul style="list-style-type: none"> <li>• Good adhesion to glass, metal, inorganic film</li> <li>• Good developability, chemical resistance, heat resistance</li> <li>• Good tack-free property before curing</li> </ul>
Non-solvent type	Product name	Polymer component (%)	Diluent type	Mw	Acid Value of polymer (mgKOH/g)	T <sub>g</sub> (°C)	Doublebond equivalent (g/mol)	Feature
	OAP-2531	35	IBXA /4-HBA	20,000	-	80	4,000	<ul style="list-style-type: none"> <li>• Good adhesion to glass, metal, inorganic film</li> <li>• Good tack-free property after curing</li> </ul>
	MAP-2801	28	Acrylic monomer	100,000	12	21	15,000	<ul style="list-style-type: none"> <li>• Good adhesion to glass, metal, inorganic film</li> <li>• Good adhesion to COP, untreated PET, PI, LCP</li> <li>• Flexible after curing</li> </ul>

## High heat resistance grade

Solvent type	Product name	Polymer component (%)	Solvent	Mw	Acid Value of polymer (mgKOH/g)	T <sub>g</sub> (°C)	Doublebond equivalent (g/mol)	Feature
	RA-4101	25	PGME	30,000	80	200	350	<ul style="list-style-type: none"> <li>• Good heat resistance, chemical resistance</li> <li>• Good developability</li> <li>• Good tack-free property</li> </ul>

## Molding Grade

Solvent type	Product name	Polymer component (%)	Solvent	Mw	Acid Value of polymer (mgKOH/g)	T <sub>g</sub> (°C)	Doublebond equivalent (g/mol)	Feature
	RA-4706	35	Butyl acetate	50,000	-	96	1,000	<ul style="list-style-type: none"> <li>• Good elongation after curing (about 200%)</li> <li>• Good chemical resistance after curing</li> </ul>

※ Mw, T<sub>g</sub> is a value at the time of trunk polymer before double bond addition.